

Lead-Free & RoHs Compliance!!

SPECIFICATION FOR APPROVAL

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|-----|-----|----|------------|

CUSTOMER P/N :

OUR DWG No:

QUANTITY :

Pcs. DATE :

ITEM :

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MPB252012T series

2015/03/02

| SPECIFICATION ACCEPTED BY: | | | | | | |
|---|---|--|--|--|--|--|
| COMPONENT ENGINEER | | | | | | |
| ELECTRICAL ENGINEER | | | | | | |
| MECHANICAL ENGINEER | | | | | | |
| APPROVED | | | | | | |
| REJECTED | | | | | | |
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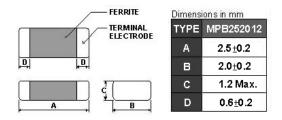
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| Part Numbering: Product Identification Image: Product Symbol Image: Pr | 1 Scope: This sp | pecification applies to Multilayer power ir | nductors |
|--|-------------------------|---|--------------------------------|
| Operating Temperature: -55°C~125°C (Including self - temperature rise) Storage Temperature: -55°C~125°C (after PCB) -5°C~40°C, Humidity 40%~70% (before PCB) 4 Marking: No Marking 5 Standard Testing Condition image Temperature Ordinary Temperature(15 to 35°C) 20±2°C | | CEC Internal No. Tolerance Inductance Packaging Dimensions code TYPE A : General B : Low RDC C : High Satura | ted Current |
| Storage Temperature: -5 °C ~ 1 2 5 °C (after PCB) -5 °C ~ 4 0 °C, Humidity 4 0% ~ 7 0% (before PCB) 4 Marking: No Marking 5 Standard Testing Condition image: image: 1 10 marking 2 10 marking 1 10 marking 1 10 marking 1 10 marking 2 10 marking 2 10 marking 3 10 marking | 3 Rating: | | |
| -5℃~40℃,Humidity 40%~70%(before PCB) 4 Marking: 5 Standard Testing Condition <u>Unless otherwise specified</u> In case of doubt <u>Temperature</u> Ordinary Temperature(15 to 35℃) 20±2℃ | Operating To | emperature: -55 °C \sim 125 °C (Inclu | uding self - temperature rise) |
| 5 Standard Testing Condition Image: Standard Testing Condition Image: Standard | | - | |
| Unless otherwise specifiedIn case of doubtTemperatureOrdinary Temperature(15 to 35℃)20±2℃ | No Marking | g | |
| TemperatureOrdinary Temperature(15 to 35℃)20±2℃ | 5 Standard Tes | | |
| | | | |
| Humidity Ordinary Humidity(25 to 85% RH) 60 to 70 % RH | | | |
| | Humidity | Ordinary Humidity(25 to 85% RH) | 60 to 70 % RH |



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6 Configuration and Dimensions:



7 ELECTRICAL CHARACTERISTICS :

| | | | | Rated | | |
|----------------------------------|------------|------------|---------|----------|-----------|--|
| Part No. | Inductance | Test Freq. | RDC | Current | Tolerance | |
| | (uH) | | (Ω)±30% | (mA)Max. | (±%) | |
| MPB252012T-R47 _D -NA2 | 0.47 | 3MHz,200mV | 0.04 | 1800 | 20,30 | |
| MPB252012T-1R0 NA2 | 1 | 3MHz,200mV | 0.05 | 1600 | 20,30 | |
| MPB252012T-1R5 -NA2 | 1.5 | 3MHz,200mV | 0.07 | 1400 | 20,30 | |
| MPB252012T-2R2 NA2 | 2.2 | 3MHz,200mV | 0.1 | 1200 | 20,30 | |
| MPB252012T-3R3 NA2 | 3.3 | 3MHz,200mV | 0.12 | 1100 | 20,30 | |
| MPB252012T-4R7 NA2 | 4.7 | 3MHz,200mV | 0.14 | 1000 | 20,30 | |
| MPB252012T-6R8 NA2 | 6.8 | 3MHz,200mV | 0.16 | 900 | 20,30 | |

NOTE: tolerance M=±20% / T=±30%

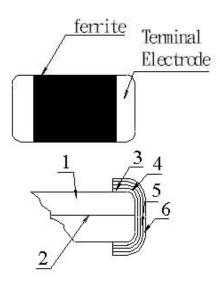
1.Operating temperature range -5.5 °C $\sim 1.2.5$ °C (Including self - temperature rise)

2.Rate Current : Applied the current to coils, the temperature rise shall not be more than $40^\circ\!\mathrm{C}$



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8.2 Material List:

| NO | PART | MATERIAL |
|----|-------------------|---------------------|
| 1 | Ferrite Substance | NiO-CuO-ZnO-Ferrite |
| 2 | Silver electrode | Ag |
| 3 | Silver electrode | Ag |
| 4 | Cu plating | Cu |
| 5 | Ni plating | Ni |
| 6 | Sn plating | Sn |



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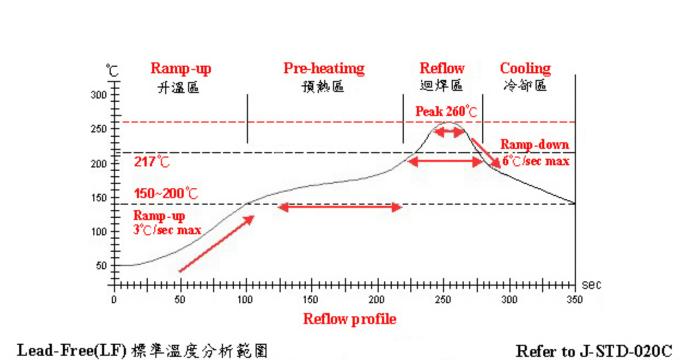
| No | lechanical Performance | Specification | Test Method | | |
|----------------------|--------------------------------|---|--|-----------|--|
| | Flexure Strength | | Test device shall be soldered on the substrate | | |
| | | conditions must not damage | Substrate Dimension: 100x40x1.6mm | | |
| | | the terminal electrode and the | ~~~~ | | |
| | | ferrite | Keeping Time: 30sec | É | |
| | | lenne | | | |
| 1-1-2 | Vibration | - | Test device shall be soldered on the substrate | | |
| | | | Oscillation Frequency: 10 to 55 to 10Hz for 1mir | n | |
| | | | Amplitude: 1.5mm | 1 | |
| | | Time: 2hrs for each axis (X, Y & Z), total 6hrs | | | |
| 1_1_3 | Resistance to Soldering Heat | Appearance: No damage | Pre-heating: 150° C, 1min | | |
| 1-1-5 | Resistance to Soldering Heat | | - | | |
| | | electrode should be covered | Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) | | |
| | | with solder. | Solder Temperature: 260±5℃ Immersion Time: 10±1sec | | |
| | | | Inmersion nime. Torrsec | | |
| | | Inductance: within ±20% of | | | |
| 1 1 1 | Saldar ability | initial value The electrodes shall be at | Dra basting: 150°C 1min | | |
| 1-1-4 Solder ability | | | Pre-heating: 150℃, 1min | | |
| | | least 95% covered with new | Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) | | |
| | | solder coating | Solder Temperature: 245±5℃ | | |
| | | | Immersion Time: 4±1sec | | |
| 1-1-5 | Terminal Strength Test | No split termination | Test device shall be soldered on the substrate, | | |
| | | | then apply a force in the direction of the arrow. | | |
| | | | Force : 5N | | |
| | | | Keeping Time: 10±1sec | | |
| | | | | | |
| | | Mounting Pad | | | |
| 1-2.E | nvironmental Performanc | e | | | |
| No | ltem | Specification | Test Method | | |
| 1-2-1 | Temperature Cycle | Appearance: No damage | One cycle: | | |
| | | Inductance:within±20% of | | ime (min) | |
| | | initial value | 1 -55±3 | 30 | |
| | | | 2 25±2 | 3 | |
| | | | 3 125±3 | 30 | |
| | | | 4 25±2 | 3 | |
| | | | Total: 100cycles | | |
| | | | Measured after exposure in the room condition f | for 24hrs | |
| | | | T | | |
| 1-2-2 | Humidity Resistance | | Temperature: 40±2℃ | | |
| 1-2-2 | Humidity Resistance | | Relative Humidity: 90 ~ 95% / Time: 1000hrs | | |
| 1-2-2 | Humidity Resistance | | | for 24hrs | |
| | Humidity Resistance High | | Relative Humidity: 90 ~ 95% / Time: 1000hrs | for 24hrs | |
| | - | | Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition f | for 24hrs | |
| | High | | Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition f Temperature: $125\pm3^{\circ}$ | | |
| 1-2-3 | High Temperature Resistance | | Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition f Temperature: 125±3°C Relative Humidity: 0% / Time: 1000hrs | | |
| | High Temperature Resistance | | Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition f Temperature: 125±3°C Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition f | | |

Measured after exposure in the room condition for 24hrs



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| 管制項目 Item. | 升溫區 Ramp-up | 預熱區 Pre-heating | 迴焊區 Reflow | Peak Temp | 冷卻區 Cooling |
|---------------------|--------------------|----------------------|---------------|-----------------|-------------------|
| 溫度範圍 Temp.scope | R.T.~150° ℃ | 150°C ~ 200°C | 21 7℃ | 260±5° C | Peak Temp. ~ 150℃ |
| 標準時間 Time spec. | - | 60 ~ 180 sec | 60 ~ 150sec | 20 ~ 40 sec | - |
| 實際時間 Time result | <u> </u> | 75 ~ 100 sec | 90 ~ 120 sec | 20 ~ 35 sec | _ |

NOTE :

1. Re-flow possible times : within 2 times

2. Nitrogen adopted is recommended while in re-flow

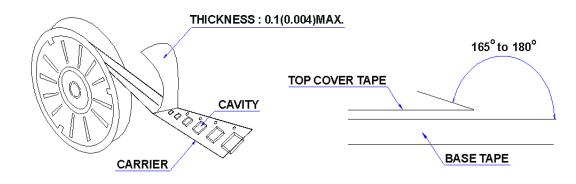


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11 PACKAGING

11.1 Packaging -Cover tape

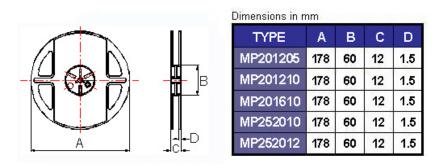
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

| TYPE | BULK | PCS/REEL |
|----------|------|----------|
| MP201205 | * | 4000 |
| MP201210 | * | 3000 |
| MP201610 | * | 3000 |
| MP252010 | * | 3000 |
| MP252012 | * | 3000 |

11.3 Reel Dimensions



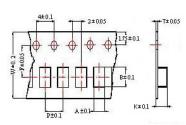


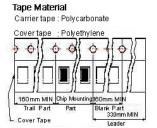
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11 PACKAGING

11.4 Tape Dimensions in mm





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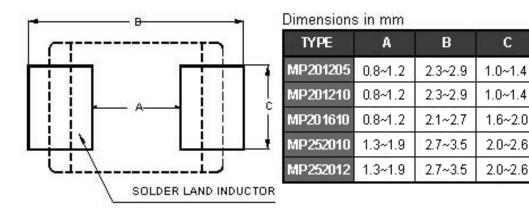
1.6~2.0

2.0~2.6

2.0~2.6

| TYPE | Α | в | т | W | Р | F | К |
|----------|------|------|------|---|---|-----|------|
| MP201205 | 1.42 | 2.25 | 0.22 | 8 | 4 | 3.5 | 0.80 |
| MP201210 | 1.45 | 2.25 | 0.22 | 8 | 4 | 3.5 | 1.04 |
| MP201610 | 1.80 | 2.20 | 0.22 | 8 | 4 | 3.5 | 1.15 |
| MP252010 | 2.25 | 2.80 | 0.25 | 8 | 4 | 3.5 | 1.35 |
| MP252012 | 2.25 | 2.80 | 0.25 | 8 | 4 | 3.5 | 1.35 |

12 Recommended Pattern



13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)



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